

06-04-2001



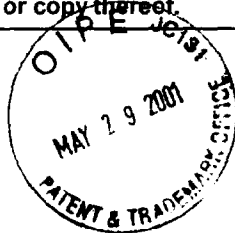
To the Honorable Commissioner of Patents and Trademarks:
Please record the attached original documents or copy thereof.

101736021
ATTN. BOX ASSIGNMENTS

1. Name of conveying party(ies):

1. Dae Gyu PARK
2. Tae Ho CHA

5.29-61



2. Name and address of receiving party(ies):

Name: HYUNDAI ELECTRONICS INDUSTRIES CO., LTD.

Internal Address:

Street Address: San 136-1, Ami-Ri, Bubal-Uep, Ichon-Shi,
Kyungki-Do, Republic of Korea

City:

State:

Zip Code:

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger

☐ Security Agreement ☐ Change of Name

☐ Other

Additional name(s) & Address(es) attached?

☐ Yes ☒ No

Execution Date: November 7, 2000

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application: _____

A. Patent Application Number(s):

09/721,636

B. Patent Number(s):

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mr. Ernest F. Chapman

Internal Address: FINNEGAN, HENDERSON, FARABOW, GARRETT
& DUNNER, L.L.P.

Street Address: 1300 I Street, N.W.

City: Washington

State: DC Zip: 20005-3315

6. Total number of applications and registrations involved:
1

7. Total fee (37 CFR 3.41): \$40

☒

Enclosed (Please charge deficiency to deposit account)

☐

Authorized to be charged to deposit account

8. Deposit account number: 06-0916

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ernest F. Chapman

May 29, 2001

Signature

Date

Total number of pages including cover sheet, attachments and documents: 2

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

METHOD OF FORMING A GATE ELECTRODE IN A SEMICONDUCTOR DEVICE

for which I/We executed an application for United States Letters Patent concurrently herewith or on _____ or filed an application for United States Letters Patent on _____, 19__ (Serial No. _____); and

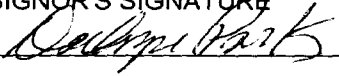
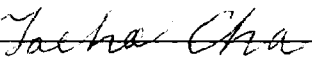
WHEREAS, **HYUNDAI ELECTRONICS INDUSTRIES CO., LTD.**, a corporation of **Republic of Korea** whose post office address is **San 136-1, Ami-Ri, Bubal-Uep, Ichon-Shi, Kyungki-Do, Republic of Korea** (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest-in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/We have empowered in the Declaration and power of Attorney in this application, to insert here in parentheses (Application No. 09/721,636, filed November 27, 2000) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/We have hereunto set our hand(s).

1. FULL NAME OF SOLE OR FIRST ASSIGNOR	: ASSIGNOR'S SIGNATURE	: DATE
<u>Dae Gyu PARK</u>	: <u></u>	: <u>November 7, 2000</u>
ADDRESS		: CITIZENSHIP
<u>Samik Apt. 104-904, Shinha-Ri, Bubal-Uep, Ichon-Shi, Kyungki-Do, Republic of Korea</u>		: <u>Republic of Korea</u>
2. FULL NAME OF SECOND ASSIGNOR	: ASSIGNOR'S SIGNATURE	: DATE
<u>Tae Ho CHA</u>	: <u></u>	: <u>November 7, 2000</u>
ADDRESS		: CITIZENSHIP
<u>Godamgisuksa 102-602, Godam-Dong, Ichon-Shi, Kyungki-Do, Republic of Korea</u>		: <u>Republic of Korea</u>

FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P. □ WASHINGTON, D.C.